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Late 1960's Plasma Asher

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A liquid organic solvent (J100) was used for removing the photoresist. In 1967, Stephan Irving of Signetics announced a method of dry ashing and removing photoresist with oxygen plasma [1]. In the same year, LFE made this method into an equipment (plasma asher). It was the first supplication of plasma in the semiconductor manufacturing process. In Japan, it was released from Tokyo Ohka in 1971 (OPM).

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